

Engineering Bill of Materials



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Project Name:	PMP10668
Project File:	PMP10668_LM3150.PrjPcb
Base ID:	
PCB Rev:	PMP10668.PcbDoc_Rev1
Schematic Rev:	PMP10668.SchDoc_Rev1
Assembly Variant:	None
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Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity	Library Name
1	Cb	CAP, CERM, DNP, 50 V, +/- 5%, C0G/NP0, 0603	Y	Kemet	C0603C102J5GAC	1	Capacitor_Ceramic.SchLib
2	Cbst	CAP, CERM, 0.47u, 16 V, +/- 10%, X5R, 0603	Y	MuRata	GRM188R61C474KA93D	1	Capacitor_Ceramic.SchLib
3	Cbyp	CAP, CERM, 0.1u, 50 V, +/- 10%, X7R, 0603	Y	MuRata	GRM188R71H104KA93D	1	Capacitor_Ceramic.SchLib
4	Cen	CAP, CERM, 1000 pF, 50 V, +/- 5%, X7R, 0603	Y	Kemet	C0603C102J5RACTU	1	Capacitor_Ceramic.SchLib
5	Cff	CAP, CERM, 820 pF, 50 V, +/- 10%, X7R, 0603	Y	Kemet	C0603C821K5RACTU	1	Capacitor_Ceramic.IntLib
6	Cin1	CAP, AL, 47u, 50 V, +/- 20%, 0.5 ohm, SMD	Y	Chemi-Con	EMVH500ADA470MJA0G	1	Capacitor_Aluminum.SchLib
7	Cin2, Cin3	CAP, CERM, 0.47u, 50 V, +/- 10%, X7R, 1206	Y	MuRata	GRM31MR71H474KA01L	2	Capacitor_Ceramic.SchLib
8	Co1	CAP, AL, 220u, 16 V, +/- 20%, 0.34 ohm, SMD	Y	Panasonic	EEE-FK1C221XP	1	Capacitor_Aluminum.SchLib
9	Co2, Co3	CAP, CERM, DNP, 16 V, +/- 20%, X7R, 1210	Y	MuRata	GRM32ER71C226ME18L	2	Capacitor_Ceramic.SchLib
10	Cr	CAP, CERM, DNP, 50 V, +/- 5%, X7R, 0603	Y	Kemet	C0603C682J5RACTU	1	Capacitor_Ceramic.IntLib
11	Css	CAP, CERM, 0.068u, 25 V, +/- 10%, X7R, 0603	Y	MuRata	GRM188R71E683KA01D	1	Capacitor_Ceramic.SchLib
12	Cvcc	CAP, CERM, 4.7u, 16 V, +/- 10%, X5R, 0603	Y	MuRata	GRM188R61C475KAAJ	1	Capacitor_Ceramic.IntLib
13	Dbst	Diode, Schottky, 40V, 3A, SMC	Y	International Rectifier	30BQ040TRPBF	1	Diode.IntLib
14	L1	Inductor, Shielded Drum Core, Ferrite, 6.8u, 8.4 A, 0.0091 ohm, SMD	Y	Würth Elektronik	7447709006	1	Inductor_Wurth.SchLib
15	Q	MOSFET, N-CH, 60 V, 8.0A, SO-8	Y	Texas Instruments	CSD88537ND	1	FETs.SchLib
16	Ren1, Ren2	RES, DNP, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06031K18FKEA	2	Resistor_0603.SchLib
17	Rfb1	RES, 4.99 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06034K99FKEA	1	Resistor_0603.SchLib
18	Rfb2	RES, 78.7 k, 0.1%, 0.1 W, 0603	Y	Yageo America	RT0603BRD0778K7L	1	Resistor_0603.SchLib
19	Rlim	RES, 1.15 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06031K15FKEA	1	Resistor_0603.SchLib
20	Rloop	RES, 10.1, 0.1%, 0.1 W, 0603	Y	Yageo America	RT0603BRD0710R1L	1	Resistor_0603.SchLib
21	Ron	RES, 383, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW0603383RFKEA	1	Resistor_0603.SchLib
22	Rr	RES, DNP, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06031K02FKEA	1	Resistor_0603.SchLib
23	Rsen1, Rsen2	RES, 1.00 k, 1%, 0.25 W, 1206	Y	Vishay-Dale	CRCW12061K00FKEA	2	Resistor_1206.IntLib
24	U1	SIMPLE SWITCHER?CONTROLLER, 42V Synchronous Step-Down, 14-pin TSSOP-EP	N	Texas Instruments	LM3150MH	1	NSC Switcher.IntLib
25	VI+, VI-, VO+, VO-	PCB Pin, TH	Y	Mill-Max	3125-2-00-34-00-00-08-0	4	Connectors.IntLib

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